DS36277

DS36277 Dominant Mode Multipoint Transceiver



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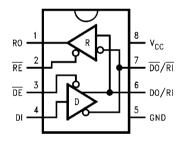
General Description

The DS36277 Dominant Mode Multipoint Transceiver is designed for use on bi-directional differential busses. It is optimal for use on Interfaces that utilize Society of Automotive Engineers (SAE) J1708 Electrical Standard.

The device is similar to standard TIA/EIA-485 transceivers, but differs in enabling scheme. The Driver's Input is normally externally tied LOW, thus providing only two states: Active (LOW), or Disabled (OFF). When the driver is active, the dominant mode is LOW, conversely, when the driver is disabled, the bus is pulled HIGH by external bias resistors.

The receiver provides a FAILSAFE feature that guarantees a known output state when the Interface is in the following conditions: Floating Line, Idle Line (no active drivers), and Line Fault Conditions (open or short). The receiver output is HIGH for the following conditions: Open Inputs, Terminated Inputs (50Ω), or Shorted Inputs. FAILSAFE is a highly desirable feature when the transceivers are used with Asynchronous Controllers such as UARTs.

Connection and Logic Diagram



Order Number DS36277TM or DS36277TN See NS Package Number M08A or N08E

Features

- FAILSAFE receiver, RO = HIGH for:
 - OPEN inputs
 - Terminated inputs
 - SHORTED inputs
- Optimal for use in SAE J1708 Interfaces
- Compatible with popular interface standards:
 - TIA/EIA-485 and TIA/EIA-422-A
 - CCITT recommendation V.11
- Bi-directional transceiver
 - Designed for multipoint transmission
- Wide bus common mode range
 __ (-7V to +12V)
- Available in plastic DIP and SOIC packages

Truth Table

Driver						
Γ	Inp	uts	Outputs			
DE		DI	DO/RI	DO /RI		
Γ	L	L	L	Н		
	L	Н	н	L		
	Н	Х	Z	Z		

Receiver					
	Inputs				
RE	RE DO/RI-DO /RI				
L	≥ 0 mV	Н			
L	≤ –500 mV	L			
L	SHORTED	н			
L	L OPEN				
н	Х	Z			

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Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage (V _{CC})	7V						
Input Voltage (\overline{DE} , \overline{RE} , and DI)	5.5V						
Driver Output Voltage/							
Receiver Input Voltage	-10V to +15V						
Receiver Output Voltage (RO)	5.5V						
Maximum Package Power Dissipation @	Maximum Package Power Dissipation @ +25°C						
N Package							
(derate 9.3 mW/°C above +25°C)	1168 mW						
M Package							
(derate 5.8 mW/°C above +25°C)	726 mW						

Storage Temperature Range	–65°C to +150°C
Lead Temperature (Soldering 4 sec.)	260°C
ESD Rating (HBM, 1.5 kΩ, 100 pF)	7.0 kV

Recommended Operating Conditions

Min	Мах	Units
4.75	5.25	V
-7	+12	V
-40	+85	°C
	4.75 –7	4.75 5.25 -7 +12

. . .

Electrical Characteristics (Notes 2, 4)

Over recommended Supply Voltage and Operating Temperature ranges, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Units	
DRIVER C	HARACTERISTICS	-			-	•		-
V _{OD}	Differential Output Voltage	I _O = 0 mA (No Load)			1.5	3.6	6	V
V _{oDO}	Output Voltage	I _O = 0 mA (Output to	GND)		0		6	V
V _{oDO}	Output Voltage				0		6	V
V _{T1}	Differential Output Voltage	R _L = 54Ω (485)	(Figure 1)	(Figure 1)		2.2	5.0	V
	(Termination Load)	R _L = 100Ω (422)			1.7	2.6	5.0	V
ΔV _{T1}	Balance of V _{T1}	R _L = 54Ω	(Note 3)		-0.2		0.2	V
	$ V_{T1} - \overline{V_{T1}} $	R _L = 100Ω			-0.2		0.2	V
V _{os}	Driver Common Mode	R _L = 54Ω	(Figure 1)		0	2.5	3.0	V
	Output Voltage	$R_{L} = 100\Omega$			0	2.5	3.0	V
ΔV _{OS}	Balance of V _{OS}	R _L = 54Ω	(Note 3)	-0.2		0.2	V	
00	$ V_{OS} - \overline{V_{OS}} $	$R_{1} = 100\Omega$			-0.2		0.2	V
V _{OH}	Output Voltage High	I _{OH} = -22 mA	(Figure 2)		2.7	3.7		V
V _{OL}	Output Voltage Low	I _{OL} = +22 mA				1.3	2	V
I _{OSD}	Driver Short-Circuit	V ₀ = +12V	(Figure 3)			92	290	mA
	Output Current	$V_{O} = -7V$				-187	-290	mA
RECEIVER	R CHARACTERISTICS		•		•	•		
V _{TH}	Differential Input High	$V_{O} = V_{OH}, I_{O} = -0.4 \text{ mA}$			-0.150	0	V	
	Threshold Voltage (Note 5)	$-7V \le V_{CM} \le +12V$						
V _{TL}	Differential Input Low	$V_{\rm O} = V_{\rm OL}, \ I_{\rm O} = 8.0 \ {\rm m}$				-0.230		V
	Threshold Voltage (Note 5)	$-7V \le V_{CM} \le +12V$						
V _{HST}	Hysteresis (Note 6)	$V_{CM} = 0V$				80		mV
I _{IN}	Line Input Current	Other Input = 0V	V ₁ = +12V			0.5	1.5	mA
	(V _{CC} = 4.75V, 5.25V, 0V)	$\overline{DE} = V_{IH} (Note 7)$	$V_1 = -7V$			-0.5	-1.5	mA
I _{OSR}	Short Circuit Current	$V_{O} = 0V$		RO	-15	-32	-85	mA
I _{oz}	TRI-STATE [®] Leakage Current	V _O = 0.4 to 2.4V			-20	1.4	+20	μA
V _{OH}	Output High Voltage	$V_{\rm ID} = 0V, \ I_{\rm OH} = -0.4$	= 0V, I _{OH} = -0.4 mA = OPEN, I _{OH} = -0.4 mA		2.3	3.7		V
	(Figure 12)	$V_{ID} = OPEN, I_{OH} = -6$			2.3	3.7		V
V _{OL}	Output Low Voltage	$V_{ID} = -0.5V, I_{OL} = +8 \text{ mA}$ $V_{ID} = -0.5V, I_{OL} = +16 \text{ mA}$				0.3	0.7	V
	(Figure 12)					0.3	0.8	V
R _{IN}	Input Resistance				10	20		kΩ

Symbol	Parameter	Conditions		Min	Тур	Max	Units
DEVICE C	HARACTERISTICS						
V _{IH}	High Level Input Voltage		DE,	2.0		V _{cc}	V
V _{IL}	Low Level Input Voltage		RE,	GND		0.8	V
I _{IH}	High Level Input Current	V _{IH} = 2.4V	or DI			20	μA
I _{IL}	Low Level Input Current	$V_{IL} = 0.4V$				-100	μA
V _{CL}	Input Clamp Voltage	I _{CL} = -18 mA			-0.7	-1.5	V
I _{cc}	Output Low Voltage	$\overline{\text{DE}} = 0\text{V}, \ \overline{\text{RE}} = 0\text{V}, \ \text{DI} = 0\text{V}$			39	60	mA
I _{CCR}	Supply Current	$\overline{\text{DE}} = 3\text{V}, \ \overline{\text{RE}} = 0\text{V}, \ \text{DI} = 0\text{V}$			24	50	mA
I _{CCD}	(No Load)	$\overline{\text{DE}} = 0\text{V}, \ \overline{\text{RE}} = 3\text{V}, \ \text{DI} = 0\text{V}$			40	75	mA
I _{CCX}		$\overline{\text{DE}} = 3\text{V}, \ \overline{\text{RE}} = 3\text{V}, \ \text{DI} = 0\text{V}$			27	45	mA

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Switching Characteristics (Note 4)

Over recommended Supply Voltage and Operating Temperature ranges, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
DRIVER CH	ARACTERISTICS	·		•	•	
t _{PLHD}	Diff. Prop. Delay Low to High	$R_L = 54\Omega$	8	17	60	ns
t _{PHLD}	Diff. Prop. Delay High to Low	C _L = 50 pF	8	19	60	ns
SKD	Diff. Skew (It _{PLHD} -t _{PHLD} I)	C _D = 50 pF		2	10	ns
r	Diff. Rise Time	(Figures 4, 5)		11	60	ns
f	Diff. Fall Time			11	60	ns
PLH	Prop. Delay Low to High	R_{L} = 27Ω, C_{L} = 15 pF		22	85	ns
PHL	Prop. Delay High to Low	(Figures 6, 7)		25	85	ns
PZH	Enable Time Z to High	R _L = 110Ω		25	60	ns
PZL	Enable Time Z to Low	C _L = 50 pF		30	60	ns
PHZ	Disable Time High to Z	(Figure 8 – Figure 11)		16	60	ns
PLZ	Disable Time Low to Z			11	60	ns
RECEIVER	CHARACTERISTICS					
PLH	Prop. Delay Low to High	$V_{ID} = -1.5V$ to +1.5V	15	37	90	ns
PHL	Prop. Delay High to Low	C _L = 15 pF	15	43	90	ns
SK	Skew (It _{PLH} –t _{PHL} I)	(Figures 13, 14)		6	15	ns
PZH	Enable Time Z to High	C _L = 15 pF		12	60	ns
PZL	Enable Time Z to Low	(Figures 15, 16)		28	60	ns
PHZ	Disable Time High to Z			20	60	ns
PLZ	Disable Time Low to Z			10	60	ns

Note 1: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the devices should be operated at these limits. The tables of "Electrical Characteristics" specify conditions for device operation.

Note 2: Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground unless otherwise specified.

Note 3: Δ |V₁₁| and Δ |V_{0S}| are changes in magnitude of V₁₁ and V_{0S}, respectively, that occur when the input changes state.

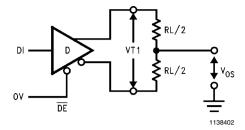
Note 4: All typicals are given for $V_{CC} = 5.0V$ and $T_A = +25^{\circ}C$.

Note 5: Threshold parameter limits specified as an algebraic value rather than by magnitude.

Note 6: Hysteresis defined as $V_{HST} = V_{TH} - V_{TL}$.

Note 7: I_{IN} includes the receiver input current and driver TRI-STATE leakage current.

Parameter Measurement Information





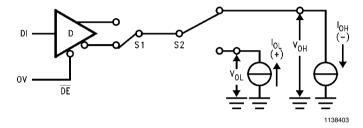


FIGURE 2. Driver $\rm V_{OH}$ and $\rm V_{OL}$ Test Circuit

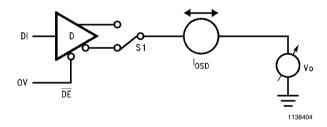
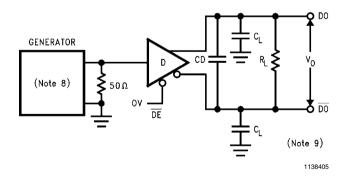
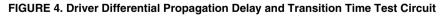


FIGURE 3. Driver Short Circuit Test Circuit





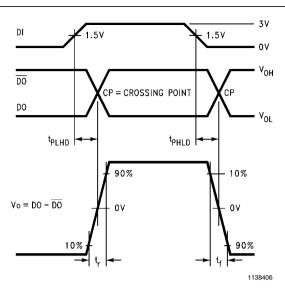


FIGURE 5. Driver Differential Propagation Delays and Transition Times

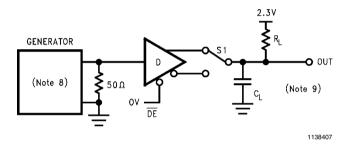


FIGURE 6. Driver Propagation Delay Test Circuit

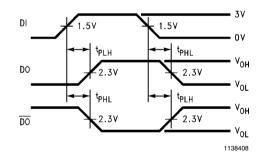
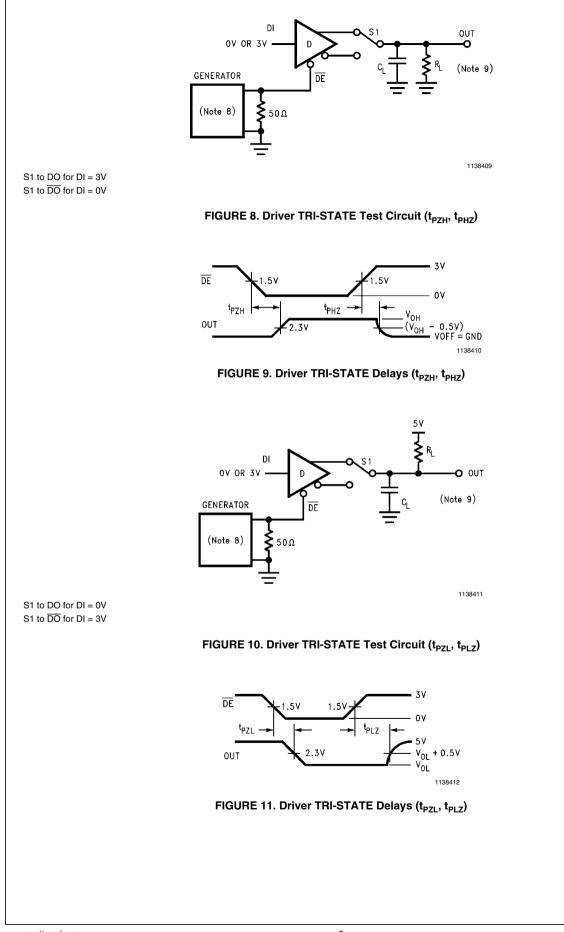


FIGURE 7. Driver Propagation Delays





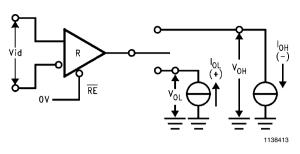


FIGURE 12. Receiver $\rm V_{OH}$ and $\rm V_{OL}$

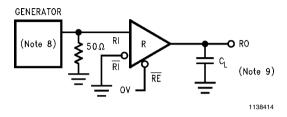


FIGURE 13. Receiver Propagation Delay Test Circuit

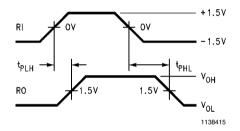


FIGURE 14. Receiver Propagation Delays

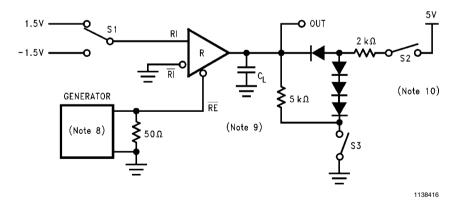
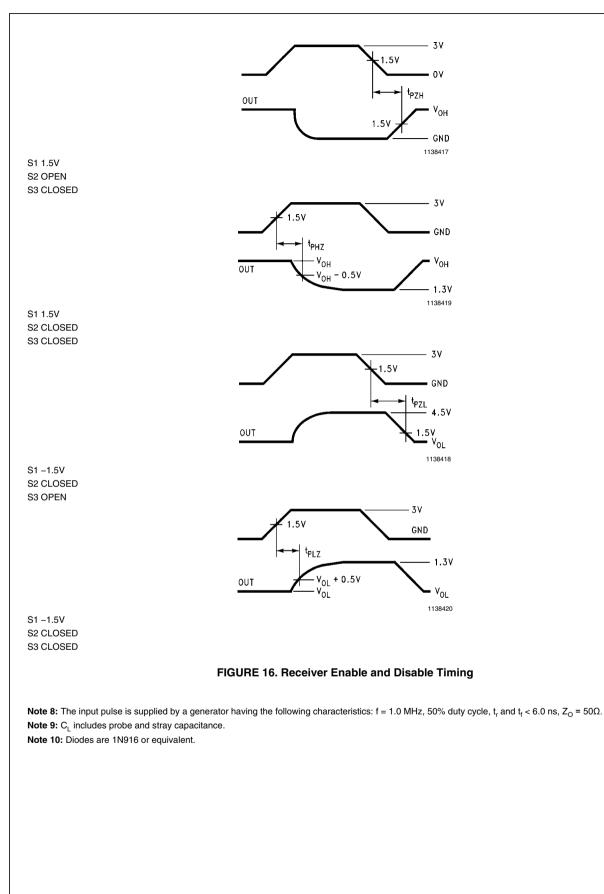
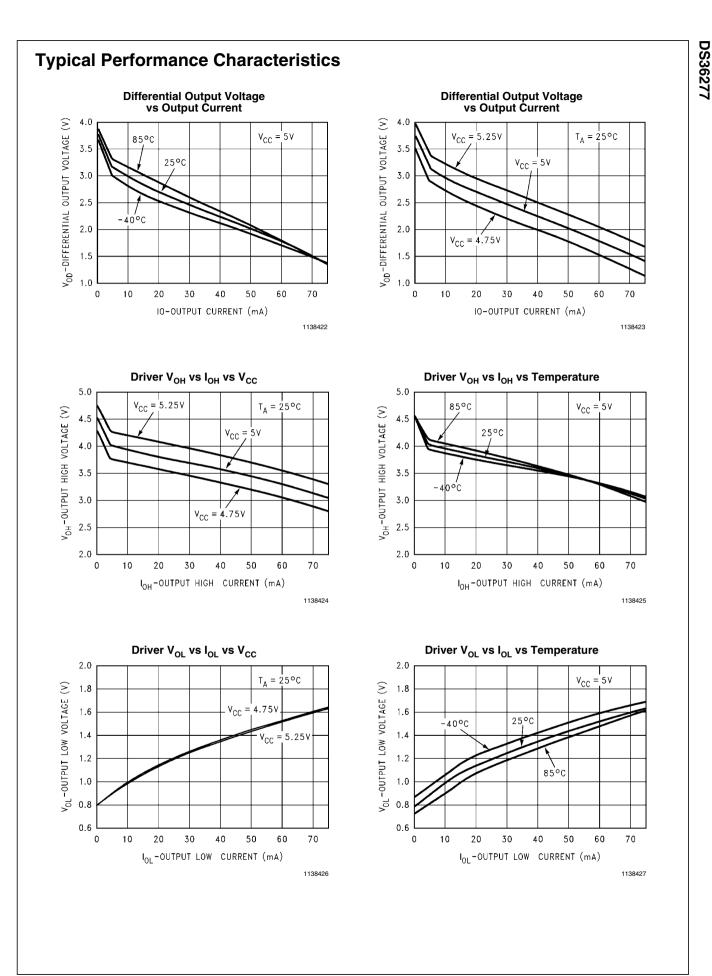


FIGURE 15. Receiver TRI-STATE Delay Test Circuit

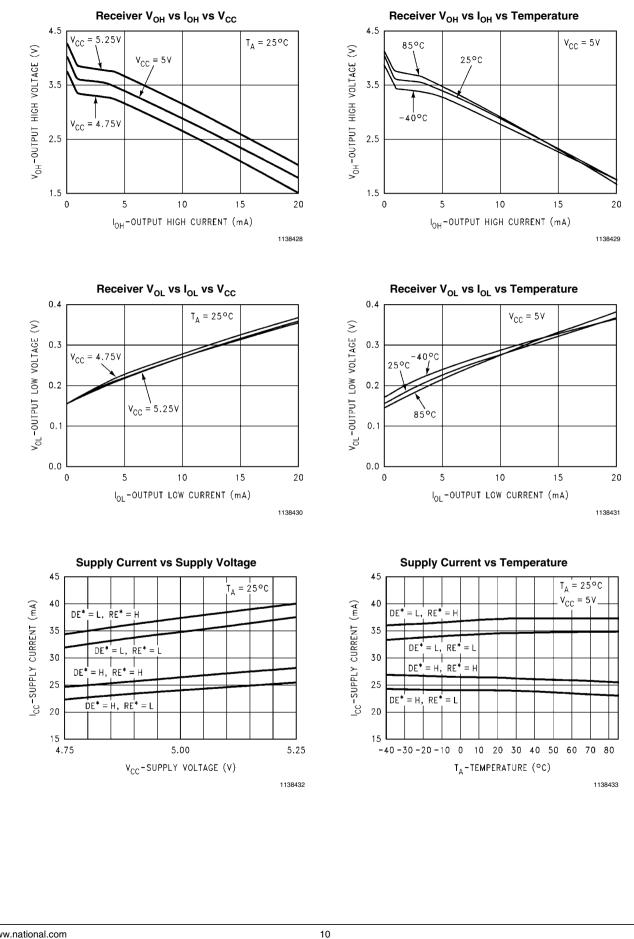
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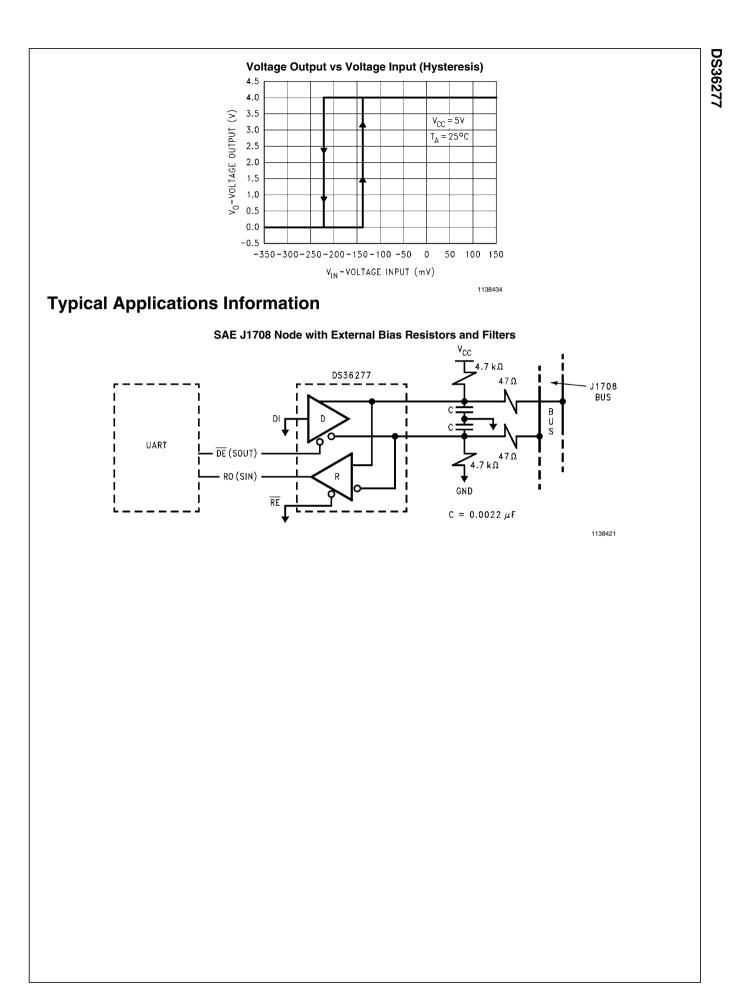


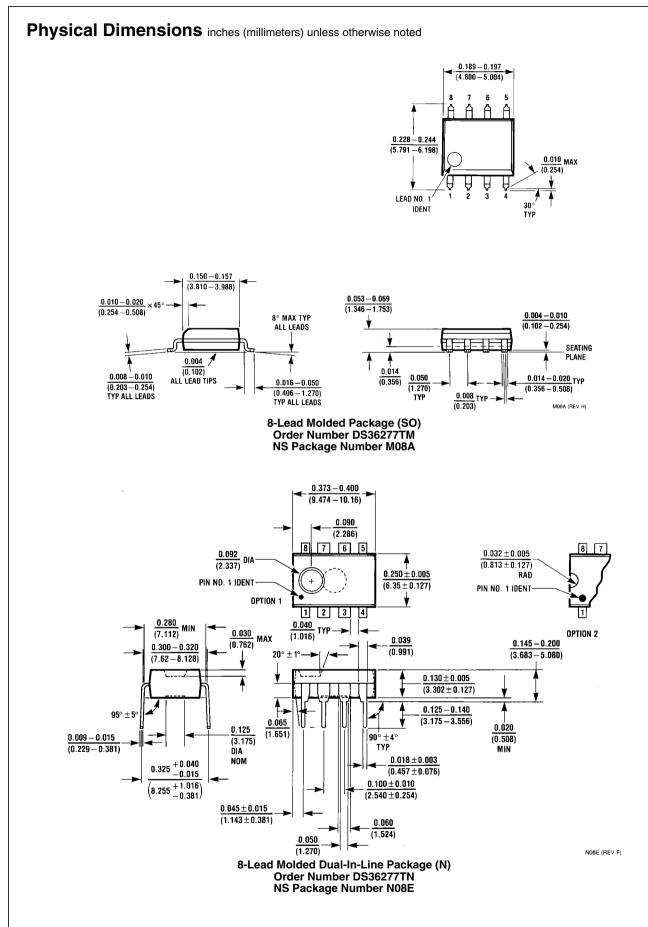


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Notes

Notes

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